# Notice for TAIYO YUDEN products

## Please read this notice before using the TAIYO YUDEN products.

## REMINDERS

### Product Information in this Catalog

Product information in this catalog is as of January 2021. All of the contents specified herein and production status of the products listed in this catalog are subject to change without notice due to technical improvement of our products, etc. Therefore, please check for the latest information carefully before practical application or use of our products.

Please note that TAIYO YUDEN shall not be in any way responsible for any damages and defects in products or equipment incorporating our products, which are caused under the conditions other than those specified in this catalog or individual product specification sheets.

### Approval of Product Specifications

Please contact TAIYO YUDEN for further details of product specifications as the individual product specification sheets are available. When using our products, please be sure to approve our product specifications or make a written agreement on the product specification with TAIYO YUDEN in advance.

### Pre-Evaluation in the Actual Equipment and Conditions

Please conduct validation and verification of our products in actual conditions of mounting and operating environment before using our products.

### Limited Application

### 1. Equipment Intended for Use

The products listed in this catalog are intended for generalpurpose and standard use in general electronic equipment (e.g., AV equipment, OA equipment, home electric appliances, office equipment, information and communication equipment including, without limitation, mobile phone, and PC) and other equipment specified in this catalog or the individual product specification sheets.

TAIYO YUDEN has the line-up of the products intended for use in automotive electronic equipment, telecommunications infrastructure and industrial equipment, or medical devices classified as GHTF Classes A to C (Japan Classes I to III). Therefore, when using our products for these equipment, please check available applications specified in this catalog or the individual product specification sheets and use the corresponding products.

### 2. Equipment Requiring Inquiry

Please be sure to contact TAIYO YUDEN for further information before using the products listed in this catalog for the following equipment (excluding intended equipment as specified in this catalog or the individual product specification sheets) which may cause loss of human life, bodily injury, serious property damage and/or serious public impact due to a failure or defect of the products and/or malfunction attributed thereto.

- (1) Transportation equipment (automotive powertrain control system, train control system, and ship control system, etc.)
- (2) Traffic signal equipment
- (3) Disaster prevention equipment, crime prevention equipment
- (4) Medical devices classified as GHTF Class C (Japan Class III)
- (5) Highly public information network equipment, dataprocessing equipment (telephone exchange, and base station, etc.)
- (6) Any other equipment requiring high levels of quality and/or reliability equal to the equipment listed above

### 3. Equipment Prohibited for Use

Please do not incorporate our products into the following equipment requiring extremely high levels of safety and/or reliability.

- (1) Aerospace equipment (artificial satellite, rocket, etc.)
- (2) Aviation equipment \*1
- (3) Medical devices classified as GHTF Class D (Japan Class IV), implantable medical devices \*<sup>2</sup>

- (4) Power generation control equipment (nuclear power, hydroelectric power, thermal power plant control system, etc.)
- (5) Undersea equipment (submarine repeating equipment, underwater work equipment, etc.)
- (6) Military equipment
- Any other equipment requiring extremely high levels of safety and/or reliability equal to the equipment listed above

### \*Notes:

- There is a possibility that our products can be used only for aviation equipment that does not directly affect the safe operation of aircraft (e.g., in-flight entertainment, cabin light, electric seat, cooking equipment) if such use meets requirements specified separately by TAIYO YUDEN. Please be sure to contact TAIYO YUDEN for further information before using our products for such aviation equipment.
- Implantable medical devices contain not only internal unit which is implanted in a body, but also external unit which is connected to the internal unit.

### 4. Limitation of Liability

Please note that unless you obtain prior written consent of TAIYO YUDEN, TAIYO YUDEN shall not be in any way responsible for any damages incurred by you or third parties arising from use of the products listed in this catalog for any equipment that is not intended for use by TAIYO YUDEN, or any equipment requiring inquiry to TAIYO YUDEN or prohibited for use by TAIYO YUDEN as described above.

### Safety Design

When using our products for high safety and/or reliability-required equipment or circuits, please fully perform safety and/or reliability evaluation. In addition, please install (i) systems equipped with a protection circuit and a protection device and/or (ii) systems equipped with a redundant circuit or other system to prevent an unsafe status in the event of a single fault for a failsafe design to ensure safety.

### Intellectual Property Rights

Information contained in this catalog is intended to convey examples of typical performances and/or applications of our products and is not intended to make any warranty with respect to the intellectual property rights or any other related rights of TAIYO YUDEN or any third parties nor grant any license under such rights.

### Limited Warranty

Please note that the scope of warranty for our products is limited to the delivered our products themselves and TAIYO YUDEN shall not be in any way responsible for any damages resulting from a failure or defect in our products. Notwithstanding the foregoing, if there is a written agreement (e.g., supply and purchase agreement, quality assurance agreement) signed by TAIYO YUDEN and your company, TAIYO YUDEN will warrant our products in accordance with such agreement.

### TAIYO YUDEN's Official Sales Channel

The contents of this catalog are applicable to our products which are purchased from our sales offices or authorized distributors (hereinafter "TAIYO YUDEN's official sales channel"). Please note that the contents of this catalog are not applicable to our products purchased from any seller other than TAIYO YUDEN's official sales channel.

### Caution for Export

Some of our products listed in this catalog may require specific procedures for export according to "U.S. Export Administration Regulations", "Foreign Exchange and Foreign Trade Control Law" of Japan, and other applicable regulations. Should you have any questions on this matter, please contact our sales staff.

# Industrial Application Guide

The products described as "For Telecommunications Infrastructure and Industrial Equipment" in this catalog are intended for use in the equipment shown in the below table as its typical example. Therefore, when using our products for these equipment, please check it carefully by referring to the part number or the individual product specification sheets and use the corresponding products. Should you have any questions on this matter, please contact us.

Category	Telecommunications Infrastructure and Industrial Equipment (Typical Example)
Telecommunications Infrastructure	<ul> <li>Base Station</li> <li>Optical Transceiver</li> <li>Router/Switch (Carrier-Grade)</li> <li>UPS (Uninterruptible Power Supply), etc.</li> </ul>
Factory Automation	<ul> <li>PLC (Programmable Logic Controller)</li> <li>Servomotor/Servo Driver</li> <li>Industry Robot, etc.</li> </ul>
Measurement	<ul> <li>Gas Meter</li> <li>Water Meter</li> <li>Flow Meter</li> <li>Pressure Gauge Meter</li> <li>Magnetometer</li> <li>Thermometer, etc.</li> </ul>
Electric Power Apparatus	<ul> <li>Power Conditioner (Solar Power System)</li> <li>Smart Meter</li> <li>GFCI (Ground Fault Circuit Interrupter)</li> <li>Electric Vehicle Charging Station, etc.</li> </ul>

Part Numbering System

Multilayer Ceramic Capacitors:



If the 15th code from the left is "8", it indicates "For Telecommunications Infrastructure and Industrial Equipment" or "For Medical Devices".

Inductors:



If the 1st code from the right is "8" regardless of the total digit number, it indicates "For Telecommunications Infrastructure and Industrial Equipment" or "For Medical Devices".

Because there are some exceptions, for details please refer to each page of this catalog where the part numbering system of each product is described.

This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our product specification sheets. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our website (http://www.ty-top.com/).

# Medical Application Guide

The products described as "For Medical Devices" in this catalog are intended for use in the medical devices classified as GHTF Classes A to C (Japan Classes I to III) except for all medical devices classified as GHTF Class D (Japan Class IV) and implantable medical devices (bone-anchored hearing aid, artificial retina system, and external unit which is connected to internal unit which is implanted in a body, etc.). Therefore, when using our products for these medical devices, please check it carefully by referring to the part number or the individual product specification sheets and use the corresponding products. Should you have any questions on this matter, please contact us.

Risk I	Level	Low					High
	Class I General Medical Devices (GHTF Class A) Medical devices with extremely low risk to the		Me (G	Class IIClass IIIControlledSpecially-controlledMedical DevicesMedical Devices(GHTF Class B)(GHTF Class		rolled ices 5 C)	Class IV Specially-controlled Medical Devices (GHTF Class D)
	PMD Rule	Medical devices with extremely low risk to the human body in case of problems	extremely low risk to the numan body in case of human body in case of		to the	Medical devices highly invasive to patients and with life-threatening risk in case of problems	
Japan	Classification according to the (based on the GHTF	[Ex.] In Vitro Diagnostic Devices Nebulizer Blood Gas Analyzer Plethysmographs Breathing Sensor AC-powered Operating Table Surgical Light Cholesterol Analysis Device Blood Type Analysis Device, etc.	Electron Gauge     Electron     Hearing     Electroc     MRI     Ultrason     Diagnost     X-ray Dia     Central	ardiograph ic Diagnostic System ic Imaging Equipment agnostic Equipment	[Ex.] • Dialysis Machine • Radiation Therapy Equipment • Infusion Pump • Respirator • Glucose Monitoring System • AED (Automated External Defibrillator) • Skin Laser Scanner • Electric Surgical Unit • Insulin Pump, etc.		[Ex.] Cardiac Pacemaker Video Flexible Angioscope Implantable Infusion Pump Cardiac Electrosurgical Unit Inspection Device with Cardiac Catheter Defibrillator, etc.
	Classification	Class I General Controls		<b>Cla</b> General Co Special (	ontrols and		Class III General Controls and Premarket Approval
U.S.A.	FDA Classif	Medical devices without the p of causing serious injury or l to the patient or user even i is a defect or malfunction in medical devices	harm f there	Medical devices w of causing injury o patient or user if th malfunction in suc	r harm to the nere is a defect or	of causir or death	devices with the possibility g serious injury, disability to the patient or user if a r malfunction occurs in such devices

Coverage of
those Classes by
TAIYO YUDEN
Products

## Product Series for Medical Devices

\*Note: It is prohibited that our products are used in some medical devices such as implantable medical devices even if such medical devices are classified as GHTF Class C (Japan Class III).

N/A

# WIRE-WOUND CHIP POWER INDUCTORS (CB SERIES)



## for High Quality Equipment

### · All the Wire-wound Chip Power Inductors of the catalog lineup are RoHS compliant.

#### Notes)

• The exchange of individual specifications is necessary depending on your application and/or circuit condition. Please contact TAIYO YUDEN's official sales channel.

• The products are for Telecommunications infrastructure and Industrial equipment and for Medical devices.

Please consult with TAIYO YUDEN's official sales channel for the details of the product specifications, etc.,

and please review and approve the product specifications before ordering.

Please be sure to contact us for further information in advance when the products are used for automotive electronic equipment.

#### 2012(0805)type

	New York I for her here a		Self-resonant	DO De l'atomos	Rated curren	t 💥) [mA]	Manager	
Part number	Nominal inductance [ µ H]	Inductance tolerance	frequency [MHz](min.)	DC Resistance $[\Omega](\pm 30\%)$	Saturation current Idc1	Temperature rise current Idc2	Measuring frequency[MHz]	Note
CB 2012T1R0M 8	1.0	±20%	100	0.15	500	700	7.96	
CB 2012T2R2M 8	2.2	±20%	80	0.23	410	620	7.96	
CB 2012T3R3M 8	3.3	±20%	55	0.30	330	550	7.96	
CB 2012T4R7M 8	4.7	±20%	45	0.40	300	430	7.96	
CB 2012T6R8M 8	6.8	±20%	38	0.47	250	350	7.96	
CB 2012T100[] 8	10	±10%, ±20%	32	0.70	190	300	2.52	
CB 2012T100[R8	10	±10%, ±20%	32	0.50	200	300	2.52	
CB 2012T150[] 8	15	±10%, ±20%	28	1.3	170	240	2.52	
CB 2012T220[] 8	22	±10%, ±20%	16	1.7	135	220	2.52	
CB 2012T470[] 8	47	±10%, ±20%	11	3.7	90	140	2.52	
CB 2012T680[] 8	68	±10%, ±20%	10	6.0	70	100	2.52	
CB 2012T101[] 8	100	±10%, ±20%	8	7.0	60	100	0.796	

	Nominal inductance		Self-resonant	DC Resistance	Rated curren	t ※)[mA]	Measuring	
Part number	[ µ H]	Inductance tolerance	frequency [MHz](min.)	$[\Omega](\pm 30\%)$	Saturation current Idc1	Temperature rise current Idc2	frequency[MHz]	Note
CB C2012T1R0M 8	1.0	±20%	100	0.19	700	640	7.96	
CB C2012T2R2M 8	2.2	±20%	70	0.33	530	485	7.96	
CB C2012T4R7M 8	4.7	±20%	45	0.50	360	395	7.96	
CB C2012T100 8	10	±10%, ±20%	40	1.2	240	255	2.52	
CB C2012T220 8	22	±10%, ±20%	16	3.7	170	145	2.52	
CB C2012T470 8	47	±10%, ±20%	11	5.8	120	115	2.52	

### 2016(0806)type

			Self-resonant	DO D	Rated curren	t ※)[mA]		
Part number	Nominal inductance [μH]	Inductance tolerance	frequency [MHz](min.)	DC Resistance [Ω](±30%)	Saturation current Idc1	Temperature rise current Idc2	Measuring frequency[MHz]	Note
CB 2016T1R0M 8	1.0	±20%	100	0.09	600	720	7.96	
CB 2016T1R5M 8	1.5	±20%	80	0.11	550	650	7.96	
CB 2016T2R2M 8	2.2	±20%	70	0.13	510	600	7.96	
CB 2016T3R3M 8	3.3	±20%	55	0.20	400	440	7.96	
CB 2016T4R7M 8	4.7	±20%	45	0.25	340	410	7.96	
CB 2016T6R8M 8	6.8	±20%	38	0.35	300	330	7.96	
CB 2016T100[] 8	10	±10%, ±20%	32	0.50	250	270	2.52	
CB 2016T150[] 8	15	±10%, ±20%	28	0.70	210	220	2.52	
CB 2016T220[] 8	22	±10%, ±20%	16	1.0	165	190	2.52	
CB 2016T330[] 8	33	±10%, ±20%	14	1.7	130	140	2.52	
CB 2016T470[] 8	47	±10%, ±20%	11	2.4	110	120	2.52	
CB 2016T680[] 8	68	±10%, ±20%	10	3.0	90	110	2.52	
CB 2016T101 8	100	±10%, ±20%	8	4.5	70	90	0.796	

	Nominal inductance		Self-resonant	DC Resistance	Rated curren	t ※)[mA]	Manualau	
Part number	Part number [ $\mu$ H]	Inductance tolerance	frequency [MHz](min.)	$[\Omega](\pm 30\%)$	Saturation current Idc1	Temperature rise current Idc2	Measuring frequency[MHz]	Note
CB C2016T1R0M 8	1.0	±20%	100	0.10	1,100	885	7.96	
CB C2016T1R5M 8	1.5	±20%	80	0.15	1,000	775	7.96	
CB C2016T2R2M 8	2.2	±20%	70	0.20	750	625	7.96	
CB C2016T3R3M 8	3.3	±20%	55	0.27	600	535	7.96	
CB C2016T4R7M 8	4.7	±20%	45	0.37	550	460	7.96	
CB C2016T6R8M 8	6.8	±20%	38	0.59	450	360	7.96	
CB C2016T100[] 8	10	±10%, ±20%	32	0.82	380	305	2.52	
CB C2016T150[] 8	15	±10%, ±20%	28	1.2	300	255	2.52	
CB C2016T220[] 8	22	±10%, ±20%	16	1.8	250	205	2.52	
CB C2016T330[] 8	33	±10%, ±20%	14	2.8	220	165	2.52	
CB C2016T470[] 8	47	±10%, ±20%	11	4.3	150	130	2.52	
CB C2016T680[] 8	68	±10%, ±20%	10	7.0	130	105	2.52	
CB C2016T101[] 8	100	±10%, ±20%	8	8.0	110	95	0.796	

Please specify the Inductance tolerance code(Kor M)

X) The saturation current value (Idc1) is the DC current value having inductance decrease down to 30% (at 20°C)
 X) The temperature rise current value (Idc2) is the DC current value having temperature increase by 20°C. (at 20°C)

X) The rated current value is following either Idc1 or Idc2, which is the lower one.

PART NUMBER

2518(1007)type			0.15		Data d aumon	it ※)[mA]		
Part number	Nominal inductance [ $\mu$ H]	Inductance tolerance	Self-resonant frequency [MHz] (min.)	DC Resistance $[\Omega](\pm 30\%)$	Rated curren Saturation current Idc1	Temperature rise current Idc2	Measuring frequency[MHz]	Note
CB 2518T1R0M 8	1.0	±20%	100	0.06	1,200	1,250	7.96	
CB 2518T1R5M 8	1.5	±20%	80	0.07	650	1,100	7.96	
CB 2518T2R2M 8	2.2	±20%	68	0.09	510	1,000	7.96	
CB 2518T3R3M 8	3.3	±20%	54	0.11	440	900	7.96	
CB 2518T4R7MR8	4.7	±20%	46	0.10	310	820	7.96	
CB 2518T4R7M 8	4.7	±20%	46	0.13	340	820	7.96	
CB 2518T6R8M 8	6.8	±20%	38	0.15	270	750	7.96	
CB 2518T100[] 8	10	±10%, ±20%	30	0.25	250	600	2.52	
CB 2518T150[] 8	15	±10%, ±20%	23	0.32	180	500	2.52	
CB 2518T220[] 8	22	±10%, ±20%	19	0.50	165	390	2.52	
CB 2518T330[] 8	33	±10%, ±20%	15	0.70	130	320	2.52	
CB 2518T470[] 8	47	±10%, ±20%	12	0.95	110	270	2.52	
CB 2518T680[] 8	68	±10%, ±20%	9.5	1.5	70	210	2.52	
CB 2518T101[] 8	100	±10%, ±20%	9.0	2.1	60	190	0.796	
CB 2518T151[] 8	150	±10%, ±20%	7.0	3.2	55	140	0.796	
CB 2518T221[] 8	220	±10%, ±20%	5.5	4.5	50	110	0.796	
CB 2518T331[] 8	330	±10%, ±20%	4.5	7.0	40	90	0.796	
CB 2518T471[] 8	470	±10%, ±20%	3.5	10	35	70	0.796	
CB 2518T681[] 8	680	±10%, ±20%	3.0	17	30	50	0.796	
CB 2518T102 8	1000	±10%, ±20%	2.4	24	25	45	0.252	

	Manager 1 for development		Self-resonant	DO Desistence	Rated curren	t 💥) [mA]	Manager	
Part number	Nominal inductance [μH]	Inductance tolerance	frequency [MHz](min.)	DC Resistance $[\Omega](\pm 30\%)$	Saturation current Idc1	Temperature rise current Idc2	Measuring frequency[MHz]	Note
CB C2518T1R0M 8	1.0	±20%	100	0.08	1,000	775	7.96	
CB C2518T1R5M 8	1.5	±20%	80	0.11	950	730	7.96	
CB C2518T2R2M 8	2.2	±20%	68	0.13	890	630	7.96	
CB C2518T3R3M 8	3.3	±20%	54	0.16	730	560	7.96	
CB C2518T4R7M 8	4.7	±20%	41	0.20	680	510	7.96	
CB C2518T6R8M 8	6.8	±20%	38	0.30	550	420	7.96	
CB C2518T100[] 8	10	±10%, ±20%	30	0.36	480	375	2.52	
CB C2518T150[] 8	15	±10%, ±20%	23	0.65	350	285	2.52	
CB C2518T220[] 8	22	±10%, ±20%	19	0.77	320	250	2.52	
CB C2518T330[] 8	33	±10%, ±20%	15	1.5	270	185	2.52	
CB C2518T470[] 8	47	±10%, ±20%	12	1.9	240	165	2.52	
CB C2518T680[] 8	68	±10%, ±20%	9.5	2.8	200	140	2.52	
CB C2518T101[] 8	100	±10%, ±20%	9.0	3.7	160	125	0.796	
CB C2518T151 8	150	±10%, ±20%	7.0	6.1	140	95	0.796	
CB C2518T221 8	220	±10%, ±20%	5.5	8.4	115	80	0.796	
CB C2518T331[] 8	330	±10%, ±20%	4.5	12.3	100	65	0.796	
CB C2518T471 8	470	±10%, ±20%	3.5	22	80	50	0.796	
CB C2518T681 8	680	±10%, ±20%	3.0	28	65	45	0.796	

### 3225(1210)type

	Manada at ta da akan sa		Self-resonant	DO De cistores	Rated curren	t ※)[mA]	Manager	
Part number	Nominal inductance [μΗ]	Inductance tolerance	frequency [MHz](min.)	DC Resistance $[\Omega](\pm 30\%)$	Saturation current Idc1	Temperature rise current Idc2	Measuring frequency[MHz]	Note
CB C3225T1R0MR8	1.0	±20%	250	0.055	2,000	1,100	0.1	
CB C3225T1R5MR8	1.5	±20%	220	0.060	2,000	1,000	0.1	
CB C3225T2R2MR8	2.2	±20%	190	0.080	2,000	930	0.1	
CB C3225T3R3MR8	3.3	±20%	160	0.095	2,000	850	0.1	
CB C3225T4R7MR8	4.7	±20%	70	0.100	1,250	830	0.1	
CB C3225T6R8MR8	6.8	±20%	50	0.120	950	760	0.1	
CB C3225T100 R8	10	±10%, ±20%	23	0.133	900	720	0.1	
CB C3225T150 R8	15	±10%, ±20%	20	0.195	730	590	0.1	
CB C3225T220 R8	22	±10%, ±20%	17	0.27	620	500	0.1	
CB C3225T330[R8	33	±10%, ±20%	13	0.41	500	400	0.1	
CB C3225T470 R8	47	±10%, ±20%	10	0.67	390	320	0.1	
CB C3225T680[R8	68	±10%, ±20%	8.0	1.0	320	260	0.1	
CB C3225T101 R8	100	±10%, ±20%	6.0	1.4	270	220	0.1	
CB C3225T221 R8	220	±10%, ±20%	3.0	2.5	190	170	0.1	
CB C3225T821 R8	820	±10%, ±20%	1.8	12	110	80	0.1	
CB C3225T102[R8	1000	±10%, ±20%	1.6	13	100	75	0.1	

• [] Please specify the Inductance tolerance code(Kor M)

%) The saturation current value (Idc1) is the DC current value having inductance decrease down to 30% ( at 20°C) %) The temperature rise current value (Idc2) is the DC current value having temperature increase by 20°C.( at 20°C) %) The rated current value is following either Idc1 or Idc2, which is the lower one.

### CB series

60% 40% 20%

> 0% -40 -20 0

Idc2

20 40 60 80

Ambient Temperature(°C)

100 120

Derating of current is necessary for CB series depending on ambient temperature. Please refer to the chart shown below for appropriate derating of current.



# WIRE-WOUND CHIP INDUCTORS (LB SERIES), WIRE-WOUND CHIP POWER INDUCTORS (CB SERIES), WIRE-WOUND CHIP INDUCTORS FOR SIGNAL LINES (LB SERIES M TYPE)

### PACKAGING

1Minimum Quantity		
	Standard Qu	antity [pcs]
Туре	Paper Tape	Embossed Tape
LB C3225	_	1000
CB C3225		1000
LB 3218	—	2000
LB R2518		
LB C2518		
LB 2518	-	2000
CB 2518		
CB C2518		
LBM2016		
LB C2016		
LB 2016	—	2000
CB 2016		
CB C2016		
LB 2012		
LB C2012		
LB R2012	—	3000
CB 2012		
CB C2012		
CB L2012	4000	_
LB 1608	4000	-
LBMF1608	_	3000
CBMF1608		0000

## 2 Tape material



This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

### i\_wound\_CB\_LB\_pack\_e-E05R01



### ③Taping Dimensions

Embossed Tape (0.315 inches wide)



<b>T</b>	Chip	cavity	Insertion pitch	Tape th	ickness
Туре	А	В	F	Т	К
LBM2016	$1.75 \pm 0.1$ (0.069 ± 0.004)	2.1±0.1 (0.083±0.004)	$4.0 \pm 0.1$ (0.157 ± 0.004)	0.3±0.05 (0.012±0.002)	1.9max. (0.075max.)
LB C3225 CB C3225	2.8±0.1 (0.110±0.004)	$3.5 \pm 0.1$ (0.138 ± 0.004)	4.0±0.1 (0.157±0.004)	0.3±0.05 (0.012±0.002)	4.0max. (0.157max.)
LB 3218	2.1±0.1 (0.083±0.004)	$3.5 \pm 0.1$ (0.138 ± 0.004)	4.0±0.1 (0.157±0.004)	0.3±0.05 (0.012±0.002)	2.2max. (0.087max.)
LB 2518 CB 2518 LB C2518 CB C2518 LB R2518	2.15±0.1 (0.085±0.004)	2.7±0.1 (0.106±0.004)	4.0±0.1 (0.157±0.004)	0.3±0.05 (0.012±0.002)	2.2max. (0.087max.)
LB 2016 CB 2016 LB C2016 CB C2016	1.75±0.1 (0.069±0.004)	2.1±0.1 (0.083±0.004)	4.0±0.1 (0.157±0.004)	0.3±0.05 (0.012±0.002)	1.9max. (0.075max.)
LB 2012 CB 2012 LB C2012 CB C2012 LB R2012	1.45±0.1 (0.057±0.004)	2.25±0.1 (0.089±0.004)	4.0±0.1 (0.157±0.004)	0.25±0.05 (0.010±0.002)	1.45max. (0.057max.)
LBMF1608 CBMF1608	$ \begin{array}{r} 1.1 \pm 0.1 \\ (0.043 \pm 0.004) \end{array} $	$1.9 \pm 0.1$ (0.075 ± 0.004)	$4.0 \pm 0.1$ (0.157 ± 0.004)	0.25±0.05 (0.010±0.002)	1.2max. (0.047max.)

Unit:mm(inch)

Card board carrier tape (0.315 inches wide)



Tune	Chip	cavity	Insertion pitch	Tape thickness
Туре	A	В	F	Т
CB L2012	$1.55 \pm 0.1$	2.3±0.1	4.0±0.1	1.1max.
CB L2012	2 (0.061±0.004) (0.09		$(0.157 \pm 0.004)$	(0.043max.)
LB 1608	$1.0 \pm 0.1$	1.8±0.1	4.0±0.1	1.1max.
LB 1608	$(0.039 \pm 0.004)$	$(0.071 \pm 0.004)$	$(0.157 \pm 0.004)$	(0.043max.)
				l lucit : mama (im ala)

Unit:mm(inch)





## 6 Top Tape Strength

The top tape requires a peel-off force 0.2 to 0.7N in the direction of the arrow as illustrated below.



# WIRE-WOUND CHIP INDUCTORS (LB SERIES), WIRE-WOUND CHIP POWER INDUCTORS (CB SERIES), WIRE-WOUND CHIP INDUCTORS FOR SIGNAL LINES (LB SERIES M TYPE)

## RELIABILITY DATA

1.Operating temper	ature Range			
	LB, LBC, LBR Series			
Specified Value	CB, CBC Series	$-40 \sim +105^{\circ}$ C (Including self-generated heat)		
	LBM Series			
Test Methods and Remarks	Including self-generated heat			
2. Storage Tempera	ture Range(after soldering)			
	LB, LBC, LBR Series			
Specified Value	CB, CBC Series	-40~+85°C		
	LBM Series			
Test Methods and Remarks	LB, CB Series: Please refer the term of "7. storage conditions" in precaution	S.		
3.Rated Current				
	LB, LBC, LBR Series			
Specified Value	CB, CBC Series	Within the specified tolerance		
	LBM Series			
4.Inductance				
	LB, LBC, LBR Series			
Specified Value	CB, CBC Series	Within the specified tolerance		
	LBM Series			
Test Methods and	LB·LBC·LBR·CB·CBC·LBM Series			
Remarks	Measuring equipment :LCR Mater (HP4285A or its e	quivalent)		
-				
5.Q				
	LB, LBC, LBR Series			
Specified Value	CB, CBC Series			
	LBM Series	Within the specified tolerance		
Test Methods and	LBM Series			
Remarks	Measuring equipment : LCR Mater(HP4285A or its eq	uivalent)		
6.DC Resistance				
	LB, LBC, LBR Series			
Specified Value	CB, CBC Series	Within the specified tolerance		
	LBM Series			
Test Methods and Remarks	Measuring equipment : DC Ohmmeter(HIOKI 3227 or its equ	ivalent)		

7.Self-Resonant Frequency				
	LB, LBC, LBR Series			
Specified Value	CB, CBC Series Within the specified tolerance			
	LBM Series			
Test Methods and Remarks	Measuring equipment : Impedance analyzer (HP4291A or its equivalent)			



8. Temperature Characteristic					
	LBM2016				Inductance change : Within±10%
	LB2012	LBR2012	CB2012	LB2016	
	CB2016	LB2518	LBR2518	CB2518	Inductance change : Within±20%
Specified Value	LBC3225	CBC3225			
	LBC2016	CBC2016	LBC2518	CBC2518	
	LB3218				Inductance change : Within±25%
	LBC2012	CBC2012			Inductance change : Within±35%
	Change of	maximum inductar	nce deviation in	step 1-5	
	Step	Temp	erature(°C)		
	Step	LB,	CB Serie		
Test Methods and	1		20		
Remarks	2		-40		
	3	20(Referen	nce temperature	e)	
	4	+85(Maximum o	operating tempe	rature)	
	5		20		

9.Rasistance to Fle	xure of Substrate		
	LB, LBC, LBR Series		
Specified Value	CB, CBC Series	No damage.	
	LBM Series		
	Warp: 2mm(LB·LBC·LBR·CB·CBC·LBM Series)Test substrate: Board according to JIS C0051Thickness: 1.0mm		
Test Methods and Remarks	Pressing jig		
	R5 45±2mm		

10.Body Strength	10.Body Strength				
	LB, LBC, LBR Series				
Specified Value	CB, CBC Series	No damage.			
	LBM Series				
Test Methods and Remarks	LB+LBC+LBR+CB+CBC+LBM Applied force : 10N Duration : 10sec.				

11.Adhesion of term	11.Adhesion of terminal electrode				
	LB, LBC, LBR Series				
Specified Value	CB, CBC Series		No abnormality.		
	LBM Series				
Test Methods and Remarks	LB•LBC•LBR•CB Applied force Duration Test substrate	•CBC•CBL•LBM : 10N to X and Y directions 5 sec. : Printed board			

12.Resistance to vibration				
Specified Value	LB, LBC, LBR Series		Inductance change : Within±20%	
	CB, CBC Series		No significant abnormality in appearance.	
	LBM Series	I Series Inductance change : Within±20% No significant abnormality in appearance.		
Test Methods and Remarks	Amplitude     : 1.5mm       Mounting method     : Soldering onto printed board			

13.Drop test			
	LB, LBC, LBR Series		
Specified Value	CB, CBC Series	—	
	LBM Series	]	

14.Solderability				
	LB, LBC, LBR Series			
Specified Value	CB, CBC Series		At least 90% of surface of terminal electrode is covered by new	
	LBM Series			
Test Methods and Remarks	LB·LBC·LBR·CB·CBC Solder temperature Duration Flux	•CBL•LBM: : 245±5°C : 5±0.5sec : Methanol solution with 25% of colo	ophony	

15.Resistance to soldering				
	LB, LBC, LBR Series	Inductance change : Within±20%		
Specified Value	CB, CBC Series			
	LBM Series	Inductance change : Within±20%		
Test Methods and Remarks	LB·LBC·LBR·CB·CBC·CBL·LBM: 3 times of reflow oven at 230°C MIN for 40sec. with peak temperature at 260 °C for 5sec.			

16.Resisitance to so	16.Resisitance to solvent				
Specified Value	LB, LBC, LBR Series				
	CB, CBC Series		-		
	LBM Series				
Test Methods and Remarks	Solvent temperature Type of solvent Cleaning conditions	: Room temperature : Isopropyl alcohol : 90s. Immersion and cleaning.			

17.Thermal shock		
Specified Value	LB, LBC, LBR Series	Inductance change : Within±20% No significant abnormality in appearance.
	CB, CBC Series	
	LBM Series	
Test Methods and Remarks	$ \begin{array}{llllllllllllllllllllllllllllllllllll$	

18.Damp heat life te	est		
Specified Value	LB, LBC, LBR Series		Inductance change : Within±20% No significant abnormality in appearance.
	CB, CBC Series		
	LBM Series		
	Temperature	: 60±2°C	
Test Methods and	Humidity	: 90~95%RH	
Remarks	Duration	: 1000 hrs	
	Recovery	: At least 2 hrs of recovery under the standard condition after the test, followed by the measurement within 48 hrs.	

19.Loading under damp heat life test			
	LB, LBC, LBR Series		Inductance change : Within±20% No significant abnormality in appearance.
Specified Value	CB, CBC Series		
	LBM Series		
Test Methods and Remarks	Temperature Humidity Duration Applied current Recovery	: 60±2°C : 90~95%RH : 1000 hrs : Rated current : At least 2 hrs of recovery under the st	andard condition after the test, followed by the measurement within 48 hrs.

20.High temperature	e life test		
	LB, LBC, LBR Ser	ies	-
Specified Value	CB, CBC Series		Inductance change : Within±20%
	LBM Series		No significant abnormality in appearance.
Test Methods and Remarks	Temperature Duration Recovery	: 85±2°C : 1000 hrs : At least 2 hrs of recovery under the sta	andard condition after the test, followed by the measurement within 48 hrs.

21.Loading at high temperature life test			
	LB, LBC, LBR Seri	es	Inductance change : Within±20% No significant abnormality in appearance.
Specified Value	CB, CBC Series		
	LBM Series		] _
	Temperature	: 85±2°C	
Test Methods and	Duration	: 1000 hrs	
Remarks	Applied current	: Rated current	
	Recovery	: At least 2 hrs of recovery under the standard condition after the test, followed by the measurement within 48 hrs.	

22.Low temperature	22.Low temperature life test			
	LB, LBC, LBR Series		Inductance change : Within±20% No significant abnormality in appearance.	
Specified Value	CB, CBC Series			
	LBM Series			
Test Methods and Remarks	Temperature Duration Recovery	: -40±2°C : 1000 hrs : At least 2 hrs of recovery under the sta	indard condition after the test, followed by the measurement within 48 hrs.	

23.Standard condit	ion	
Specified Value	LB, LBC, LBR Series	Standard test conditions
	CB, CBC Series	Unless specified, Ambient temperature is $20\pm15^{\circ}$ C and the Relative
	LBM Series	humidity is 65±20%. If there is any doubt about the test results, further measurement shall be had within the following limits: Ambient Temperature: 20±2°C Relative humidity: 65±5% Inductance value is based on our standard measurement systems.

## WIRE-WOUND CHIP INDUCTORS (LB SERIES), WIRE-WOUND CHIP POWER INDUCTORS (CB SERIES), WIRE-WOUND CHIP INDUCTORS FOR SIGNAL LINES (LB SERIES M TYPE)

### PRECAUTIONS

1. Circuit Design	1
Precautions	<ul> <li>Operating environment</li> <li>The products listed in this catalogue are intended for use in general electronic equipment (e.g., AV equipment, OA equipment, home electric appliances, office equipment, information and communication equipment), general medical equipment, industrial equipment, and automotive interior applications, etc.</li> <li>Please be sure to contact TAIYO YUDEN for further information before using the products for any equipment which may directly cause loss of human life or bodily injury (e.g., specially controlled medical equipment, transportation equipment including, without limitation, automotive powertrain control system, train control system, and ship control system, traffic signal equipment).</li> <li>Please do not incorporate our products into any equipment requiring high levels of safety and/or reliability (e.g., aerospace equipment, aviation equipment, nuclear control equipment, undersea equipment, military equipment, etc.).</li> </ul>

2. PCB Design	
Precautions	<ul> <li>◆Land pattern design</li> <li>1. Please contact any of our offices for a land pattern, and refer to a recommended land pattern of a right figure or specifications.</li> </ul>
Technical considerations	PRECAUTIONS [Recommended Land Patterns] Surface Mounting • Mounting and soldering conditions should be checked beforehand. • Applicable soldering process to those products is reflow soldering only.

3. Consideration	3. Considerations for automatic placement		
Precautions	<ul> <li>Adjustment of mounting machine</li> <li>1. Excessive impact load should not be imposed on the products when mounting onto the PC boards.</li> <li>2. Mounting and soldering conditions should be checked beforehand.</li> </ul>		
Technical considerations	1. When installing products, care should be taken not to apply distortion stress as it may deform the products.		

4. Soldering			
Precautions	<ul> <li>Reflow soldering(LB and CB Types)         <ol> <li>For reflow soldering with either leaded or lead-free solder, the profile specified in "point for controlling" is recommended.</li> <li>Recommended conditions for using a soldering iron                 <ul> <li>Put the soldering iron on the land-pattern. Soldering iron's temperature - Below 350°C Duration-3 seconds or less. The soldering should not come in contact with inductor directly.</li> </ul> </li> </ol></li></ul>		
Technical considerations	<ul> <li>Reflow soldering( LB and CB Types)         <ol> <li>Reflow profile</li> <li>Reflow profile</li> <li>Reflow profile</li> <li>Sec max</li> <li>Peak:</li> <li>200</li> <li>90±30sec</li> <li>30±10sec</li> <li>30±10sec</li> <li>Heating Time [sec]</li> </ol> </li> <li>Recommended conditions for using a soldering iron         <ol> <li>Components can be damaged by excessive heat where soldering conditions exceed the specified range.</li> </ol> </li> </ul>		

5. Cleaning	
Precautions	♦Cleaning conditions Washing by supersonic waves shall be avoided.
Technical considerations	<ul> <li>♦Cleaning conditions</li> <li>If washed by supersonic waves, the products might be broken.</li> </ul>

6. Handling	
Precautions	<ul> <li>Handling <ol> <li>Keep the inductors away from all magnets and magnetic objects.</li> <li>Breakaway PC boards (splitting along perforations)</li> <li>When splitting the PC board after mounting inductors, care should be taken not to give any stresses of deflection or twisting to the board.</li> <li>Board separation should not be done manually, but by using the appropriate devices.</li> <li>Mechanical considerations <ol> <li>Please do not give the inductors any excessive mechanical shocks.</li> </ol> </li> </ol></li></ul>
Technical considerations	<ul> <li>Handling</li> <li>1. There is a case that a characteristic varies with magnetic influence.</li> <li>Breakaway PC boards (splitting along perforations)</li> <li>1. Planning pattern configurations and the position of products should be carefully performed to minimize stress.</li> <li>Mechanical considerations</li> <li>1. There is a case to be damaged by a mechanical shock.</li> </ul>

7. Storage conditions	
Precautions	<ul> <li>Storage         <ol> <li>To maintain the solderability of terminal electrodes and to keep the packing material in good condition, temperature and humidity in the storage area should be controlled.             <ul> <li>Recommended conditions</li></ul></li></ol></li></ul>
Technical considerations	<ul> <li>Storage</li> <li>Under a high temperature and humidity environment, problems such as reduced solderability caused by oxidation of terminal electrodes and deterioration of taping/packaging materials may take place.</li> </ul>